

NRZ

(0.80 mm) .0315" PITCH • QTE/QSE SERIES

QTE **Board Mates:** OSF

QSE Board Mates: OTF

QTE/QSE

Cable Mates: EQCD, EQDP

Standoffs: SO

SPECIFICATIONS

Insulator Material: Liquid Crystal Polymer Contact Material: Phosphor Bronze Plating: Au or Sn over 50 μ" (1.27 μm) Ni Current Rating: Contact: 2 A per pin (2 pins powered) **Ground Plane:** Ground Plane:
23 A per ground plane
(1 ground plane powered)
Operating Temp Range:
-55 °C to +125 °C
Voltage Rating:
225 VAC when mated
& 5 mm Stack Height Max Cycles:

QTE -	PINS PER ROW NO. OF PAIRS
	-020, -040, -060 (40 total pins per bank = -D)

-014, -028, -042 (14 pairs per bank = -D-DP)

Specify -F **LEAD** = Gold flash on contact, Matte Tin on tail **STYLE** from Chart

LEAD

STYLE

10 μ" (0.25 μm) Gold on contact, Matte Tin on tail

PLATING

OPTION

-C = 50 μ" (1.27 mm) Electro-Polished Selective Gold on contact, Matte Tin on tail (passes 10 year MFG testing)

-D = Single-

TYPE

Ended -D-DP = Differential Pair (-01 only)

= (7.00 mm) .275" DIA Polyimide film Pick & Place Pad

OTHER

OPTIONS

-K

-L= Latching Option (N/A on –042 & -060 positions)

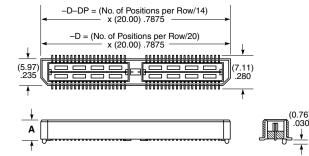
-TR =Tape & Reel (N/A -05 to -07 lead style)

"X"R

= Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks) (N/A -05 to -07 lead style)

QTE LEAD STYLE	A	HEIGHT WITH QSE*
-01	(4.27) .168	(5.00) .197
-02	(7.26) .286	(8.00) .315
-03	(10.27) .404	(11.00) .433
-04	(15.25) .600	(16.00) .630
-05	(18.26) .718	(19.00) .748
-07	(24.24) .954	(25.00) .984
-09	(13.26) .522	(14.00) .551

*Processing conditions will affect mated height. See SO Series for board space tolerances



View complete specifications at: samtec.com?QTE

PROCESSING

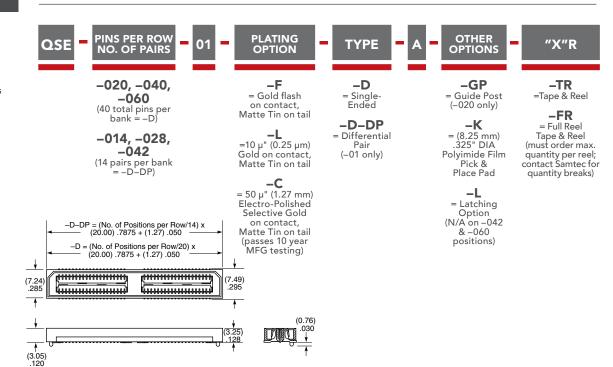
Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (020-060)

Board Stacking:

For applications requiring more than two connectors contact ipg@samtec.com





Note:

Some lengths, styles and options are non-standard, non-returnable.

View complete specifications at: samtec.com?QSE